



Material Content Data Sheet



Sales Product Name		1ED110I12MF		Issued		20. July 2018		
MA#		MA001245992						
Package		PG-DSO-8-51		Weight*		80.39 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.235	2.78	2.78	27802	27802
leadframe	inorganic material	phosphorus	7723-14-0	0.008	0.01		103	
	non noble metal	zinc	7440-66-6	0.033	0.04		410	
	non noble metal	iron	7439-89-6	0.660	0.82		8207	
wire	non noble metal	copper	7440-50-8	26.789	33.32	34.19	333233	341953
	noble metal	gold	7440-57-5	0.228	0.28	0.28	2832	2832
	encapsulation	organic material	carbon black	1333-86-4	0.146	0.18		1818
plastics	plastics	epoxy resin	-	4.725	5.88		58777	
	inorganic material	silicondioxide	60676-86-0	43.842	54.55	60.61	545354	605949
leadfinish	non noble metal	tin	7440-31-5	0.814	1.01	1.01	10123	10123
plating	noble metal	silver	7440-22-4	0.095	0.12	0.12	1185	1185
glue	plastics	acrylic resin	-	0.180	0.22		2234	
	noble metal	silver	7440-22-4	0.637	0.79	1.01	7922	10156
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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